



AMD Instinct™ MI300X Firmware Changes

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Chapter 1: Introduction

This document provides release notes for the AMD Instinct™ MI300X accelerator firmware, including enhancements and key fixes.

Chapter 2: Release Contents

The following table details the versions of the constituent firmware and software components in this release. The **Previous Component Details** are included for reference and represent the component details from the previous release. For convenience, any versions that have changed since the previous release are highlighted. Some versions may remain unchanged across different releases.

Table 2-1 Firmware Bundle Component Versions

Location	Component	Component Details	Previous Component Details	Version Number
Bundle	bundle_active	01.25.02.04 (Production)	01.25.01.08 (Production)	0x01190204
Bundle	ROT	00770000 (Production)	00770000 (Production)	0x00770000
Bundle	IFWI	01.09.151100	01.08.150641	0x10924E3C
Bundle	SMC	2.11.0.74.2F (Production)	2.11.0.72.6F (Production)	0x01004A2F
		2.11.0.75.2F (Production)	2.11.0.73.6F (Production)	0x01004B2F
Bundle	SMC FPGA	00.26.10	00.26.10	0x00026010
Bundle	UBB FPGA	00.26.13	00.26.13	0x00026013
		00.26.24	00.26.24	0x00026024
Bundle	Retimer	2.11.062	2.11.062	0x0200B03E
		2.11.076	2.11.076	0x0200B04C
		2.11.077	2.11.077	0x0200B04D
		2.11.078	2.11.078	0x0200B04E
		2.11.083	2.11.083	0x0200B053
Bundle	Remote Management	4.0.16	4.0.16	0x04000010
Bundle	VR	01.009 (with SMC 2.11.0.74.2)	01.009 (with SMC 2.11.0.72.6)	01.009
		02.0BE (with SMC 2.11.0.74.2)	02.0BE (with SMC 2.11.0.72.6)	02.0BE
		01.00A (with SMC 2.11.0.75.2)	01.00A (with SMC 2.11.0.73.6)	01.00A
		02.0CE (with SMC 2.11.0.75.2)	02.0CE (with SMC 2.11.0.73.6)	02.0CE



Chapter 3: Enhancements

If there are enhancements, the following table details them, organized by domain.

Table 3-1 Enhancements

AMD Ref ID	Domain	Description
P173845	General	Added an identifier for whether a CPER error detected was due to scrub or non-scrub in decoded ADDC CDUMP Analyzer output. This identifier is also visible through Redfish dump entries when the “ShowACAErrData” feature is enabled.
S518775	General	Added support for DPX mode with NPS2 memory mode. Consult ROCm 6.4.1 release notes for more information.

Chapter 4: Key Fixes

The tables below detail the key fixes in this release, if present, sorted by domain. The "Fixed Known Issues" table includes previously documented issues that have been resolved in this release. The "Fixed New Issues" table lists issues that were not previously documented but have been resolved in this release.

Table 4-1 Fixed Known Issues

AMD Ref ID	Domain	Issue	Fix
P172692	General	Intermittent OAM fatal errors while running workloads	Improved Data Fabric stability settings for cross-die traffic.
P171690	Virtualization	Guest KVM amdgpu driver load timeout with Call Trace	Modified PMFW to RLC handshake sequence.

Table 4-2 Fixed New Issues

AMD Ref ID	Domain	Issue	Fix
P176292	RAS	Spurious GFX UEs when injecting other types of errors	In ROCm 6.4.1, corrected GPU driver logic to differentiate DE/poison from UE and prevented GFX UE counts from increasing on poison injections.
U2591	SMC	Missing poison identifier for poison consumption in ACA decoded data through Redfish	When the "ShowACAErrData" feature is enabled, on poison consumptions the poison identifier is now set in ErrDataArr→DecodedData.
U2648	SMC	Incorrect OAM number reported in ACA decoded data through Redfish	When the "ShowACAErrData" feature is enabled, CPER dump entries will specify the correct OAM at fault under ErrDataArr→error_location instead of always reporting OAM 0.
U2864	SMC	OAM sensors are getting stuck	Rarely, an OAM may encounter a problem where the primary interface used to read the GPU die temperature may fail. In these situations, a secondary interface is now used to read the GPU die temperatures.



Appendix A: Notices

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